# **Schottky Barrier Diode**

These Schottky barrier diodes are designed for high speed switching applications, circuit protection, and voltage clamping. Extremely low forward voltage reduces conduction loss. Miniature surface mount package is excellent for hand held and portable applications where space is limited.

#### **Features**

- Extremely Fast Switching Speed
- Extremely Low Forward Voltage -0.28 Volts (Typ) @  $I_F = 1$  mAdc
- Low Reverse Current
- Pb-Free Package is Available



# ON Semiconductor®

http://onsemi.com

# 40 V SCHOTTKY BARRIER DIODE



#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Peak Reverse Voltage	V <sub>RM</sub>	40	V
Reverse Voltage	V <sub>R</sub>	30	Vdc
Forward Continuous Current (DC)	I <sub>F</sub>	30	mA
Peak Forward Surge Current	I <sub>FSM</sub>	500	mA
Electrostatic Discharge	E <sub>SD</sub>	HBM Class: 1C MM Class: A	

# THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR–5 Board, (Note 1.) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	200 1.57	mW mW/°C
Thermal Resistance Junction–to–Ambient	$R_{\theta JA}$	635	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

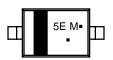
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. FR-5 Minimum Pad



SOD-323 CASE 477 STYLE 1

#### **MARKING DIAGRAM**



5E = Specific Device Code

M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

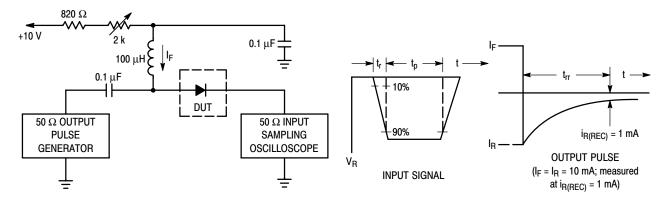
#### **ORDERING INFORMATION**

Device	Package Shipping			
RB751V40T1	SOD-323	3000/Tape & Reel		
RB751V40T1G	SOD-323 (Pb-Free)	3000/Tape & Reel		

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

# **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

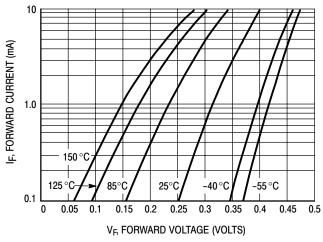
Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Breakdown Voltage $(I_R = 10 \mu A)$	V <sub>(BR)R</sub>	30	-	-	Volts
Total Capacitance (V <sub>R</sub> = 1.0 V, f = 1.0 MHz)	C <sub>T</sub>	-	2.0	2.5	pF
Reverse Leakage (V <sub>R</sub> = 30 V)	I <sub>R</sub>	-	300	500	nAdc
Forward Voltage (I <sub>F</sub> = 1.0 mAdc)	V <sub>F</sub>	-	0.28	0.37	Vdc



Notes: 1. A 2.0 k $\Omega$  variable resistor adjusted for a Forward Current (I<sub>F</sub>) of 10 mA. 2. Input pulse is adjusted so I<sub>R(peak)</sub> is equal to 10 mA.

- 3.  $t_p \gg t_{rr}$

Figure 1. Recovery Time Equivalent Test Circuit



1000 T<sub>A</sub> = 150°C  $I_{R}$ , REVERSE CURRENT ( $\mu A$ ) 100 125°C 10 85°C = 1.0 0.1 25°C 0.01 0.001 15 20 25 30 35 V<sub>R</sub>, REVERSE VOLTAGE (VOLTS)

Figure 2. Typical Forward Voltage

Figure 3. Reverse Current versus Reverse Voltage

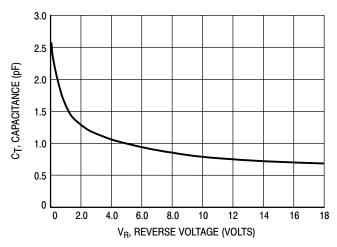
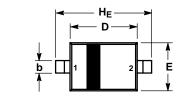
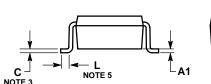


Figure 4. Typical Capacitance

#### PACKAGE DIMENSIONS

SOD-323 CASE 477-02 ISSUE G







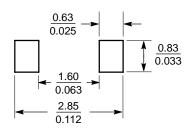
#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
   MALEMAN AND TOLERANCING PER ANSI
- Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETERS.
- LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.
- 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
- DIMENSION L IS MEASURED FROM END OF RADIUS.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.80	0.90	1.00	0.031	0.035	0.040	
A1	0.00	0.05	0.10	0.000	0.002	0.004	
A3	0.15 REF			0.006 REF			
b	0.25	0.32	0.4	0.010	0.012	0.016	
С	0.089	0.12	0.177	0.003	0.005	0.007	
D	1.60	1.70	1.80	0.062	0.066	0.070	
E	1.15	1.25	1.35	0.045	0.049	0.053	
L	0.08			0.003			
HE	2.30	2.50	2.70	0.090	0.098	0.105	

STYLE 1: PIN 1. CATHODE 2. ANODE

#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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